

GENERAL DESCRIPTION

The CMT2301 is the P-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology. ◆

This high density process is especially tailored to minimize on-state resistance.

These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits, and low in-line power loss are needed in a very small outline surface mount package.

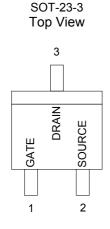
FEATURES

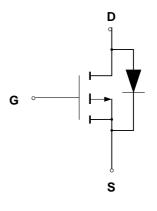
- -20V/-2.3A , $R_{DS(ON)}$ =130 mΩ@VGS=-4.5V
- -20V/-1.9A ,R_{DS(ON)}=190 mΩ@VGS=-2.5V
- ◆ Super high density cell design for extremely low R_{DS(ON)}
- Exceptional on-resistance and maximum DC current capability
- SOT-23-3 package design

APPLICATIONS

- ◆ Power Management in Notebook
- Portable Equipment
- Battery Powered System
- ♦ DC/DC Converter
- ♦ Load Switch
- DSC
- ♦ LCD Display inverter

PIN CONFIGURATION SYMBOL





P-Channel MOSFET

ORDERING INFORMATION

Part Number	Package
CMT2301M233	SOT-23-3
CMT2301GM233*	SOT-23-3

*Note: G : Suffix for Pb Free Product



ABSOLUTE MAXIMUM RATINGS

Rating			Value	Unit	
Drain- to- Source Voltage			-20	V	
Gate-to-Source Voltage		V _{GSS}	±8	V	
Continuous Dunin Current/T -150°C)	T _A =25°C		-2.5	Α	
Continuous Drain Current(T _J =150°ℂ)	T _A =70°C	l _D	-1.5		
Pulsed Drain Current		I _{DM}	-10	Α	
Continuous Source Current(Diode Conduction)		I _S	-1.6	Α	
Deves Dissipation	T _A =25°C	_	1.25	W	
Power Dissipation	T _A =70°C	P _D	0.8		
Operating Junction Temperature		TJ	150	$^{\circ}\mathbb{C}$	
Storage Temperature Range		T _{STG}	-55/150	$^{\circ}\!\mathbb{C}$	
Thermal Resistance-Junction to Ambient			120	°C/W	

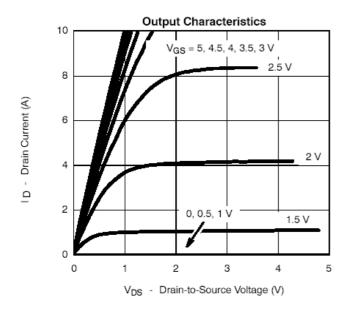
ELECTRICAL CHARACTERISTICS

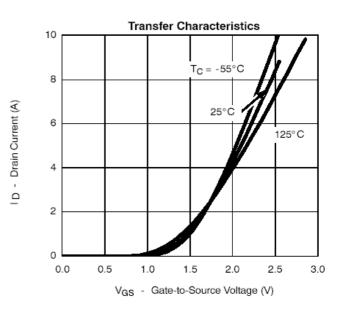
Unless otherwise specified, $T_J = 25^{\circ}C$.

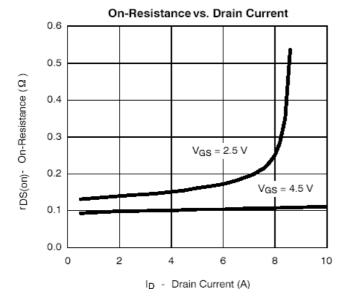
			CMT2301				
Chai	racteristic	Symbol	Min	Тур	Max	Units	
Static							
Drain-Source Breakdown Voltage		$V_{(BR)DSS}$	-20			V	
$(V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{ A})$		V (BR)DSS				V	
Gate Threshold Voltage		V _{GS(th)}	-0.45		-1.5	V	
$(V_{DS} = V_{GS}, I_D = -250 \mu A)$						V	
Gate Leakage Current		I _{GSS}			±100	nA	
$(V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V})$	IGSS						
Zero Gate Voltage Drain Current							
$(V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V})$		I _{DSS}			-1	μA	
$(V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55^{\circ}\text{C})$					-10		
On-State Drain Current							
$(V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{V})$		$I_{D(on)}$	-6			Α	
$(V_{DS} \le -5 \text{ V}, V_{GS} = -2.5 \text{V})$			-3				
Drain-Source On-Resistance							
$(V_{GS} = -4.5 \text{ V}, I_D = -2.8 \text{A})$		R _{DS(on)}		0.105	0.13	Ω	
$(V_{GS} = -2.5 \text{ V}, I_D = -2.0 \text{A})$				0.145	0.19		
Forward Transconductance (V _{DS} = -5 V, I _D = -2.8V)		g FS		6.5		S	
Diode Forward Voltage (I _S =-1.6A,V _{GS} =0V)		V_{SD}		-0.8	-1.2	V	
Dynamic		1		1		1	
Input Capacitance	$(V_{DS} = -6 \text{ V}, V_{GS} = -0 \text{ V},$	C _{iss}		415		pF	
Output Capacitance	f = 1.0 MHz	Coss		223			
Reverse Transfer Capacitance	1.5 WH2)	C _{rss}		87			
Turn-On Time Turn-Off Time	$(V_{DD} = -6 \text{ V}, R_L = 6\Omega)$	$t_{d(on)}$		13	25	ns	
	$(V_{DD} = -6 \text{ V}, R_L = 6\Omega)$ $I_D = -1.0 \text{ A}, V_{GEN} = -4.5 \text{ V},$ $R_G = 6\Omega)$	tr		36	60		
		$t_{d(off)}$		42	70		
Turri-On Time	$\kappa_{\rm G} = 0\Omega$)			34	60		
Total Gate Charge	()/ = 6)/ 1 = 2 9 ^	Q_g		5.8	10		
Gate-Source Charge	$(V_{DS} = -6 \text{ V}, I_{D} = -2.8 \text{ A}, V_{GS} = -4.5 \text{V})$	Q_gs		0.85		nC	
Gate-Drain Charge	V _{GS} =-4.5V)	Q_{gd}		1.7			

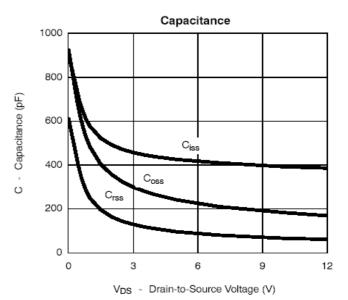


TYPICAL CHARACTERISTICS



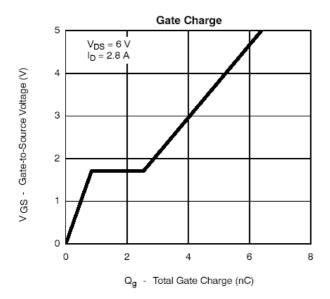


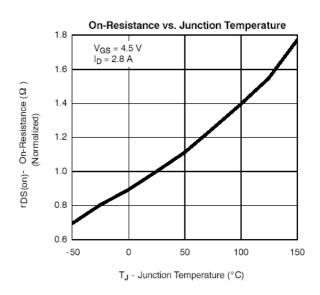


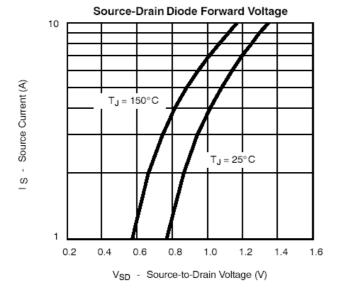


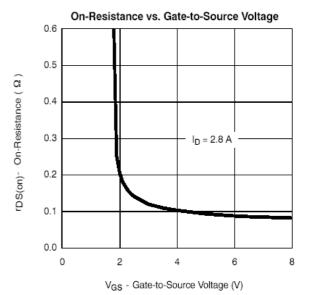


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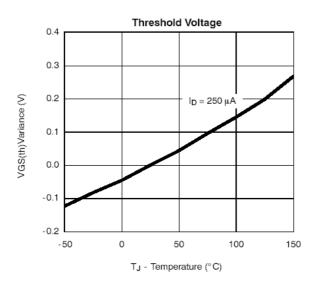


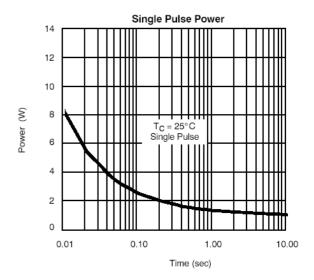


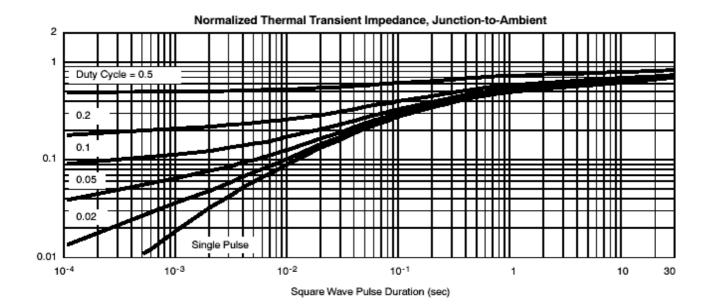




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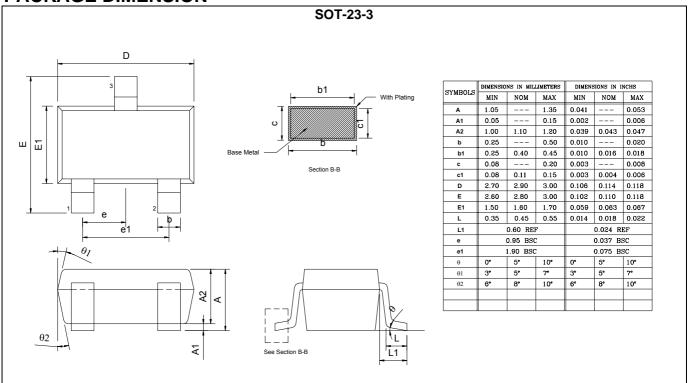








PACKAGE DIMENSION





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